



Material Content Data Sheet



Sales Product Name		SP370-25-106-0		Issued		29. August 2013			
MA#		MA000979032							
Package		PG-DSOSP-14-64		Weight*		620.40 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	28.549	4.60	4.60	46017	46017	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		71		
		non noble metal	zinc	7440-66-6	0.176	0.03		283	
		non noble metal	iron	7439-89-6	3.511	0.57		5660	
wire	noble metal	non noble metal	copper	7440-50-8	142.572	22.98	23.59	229805	235819
		noble metal	gold	7440-57-5	0.941	0.15	0.15	1517	1517
		organic material	carbon black	1333-86-4	0.820	0.13		1322	
encapsulation	plastics	epoxy resin	-	44.294	7.14		71395		
		inorganic material	silicondioxide	60676-86-0	365.014	58.84	66.11	588349	661066
leadfinish	non noble metal	tin	7440-31-5	4.526	0.73	0.73	7295	7295	
plating	noble metal	silver	7440-22-4	2.637	0.42	0.42	4250	4250	
glue	plastics	maleimide resin	-	5.464	0.88		8807		
		noble metal	silver	7440-22-4	21.856	3.52	4.40	35229	44036
*deviation	< 10%				Sum in total:	100,00		1000000	

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com